

# SOT2162-1

VFBGA59, very thin fine-pitch ball grid array package, 59 terminals, 0.4 mm pitch, 4 mm x 4 mm x 0.77 mm body

2 March 2022

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	VFBGA59
<b>Package style descriptive code</b>	VFBGA (very thin fine-pitch ball grid array)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	02-09-2022
<b>Manufacturer package code</b>	98ASA01815D

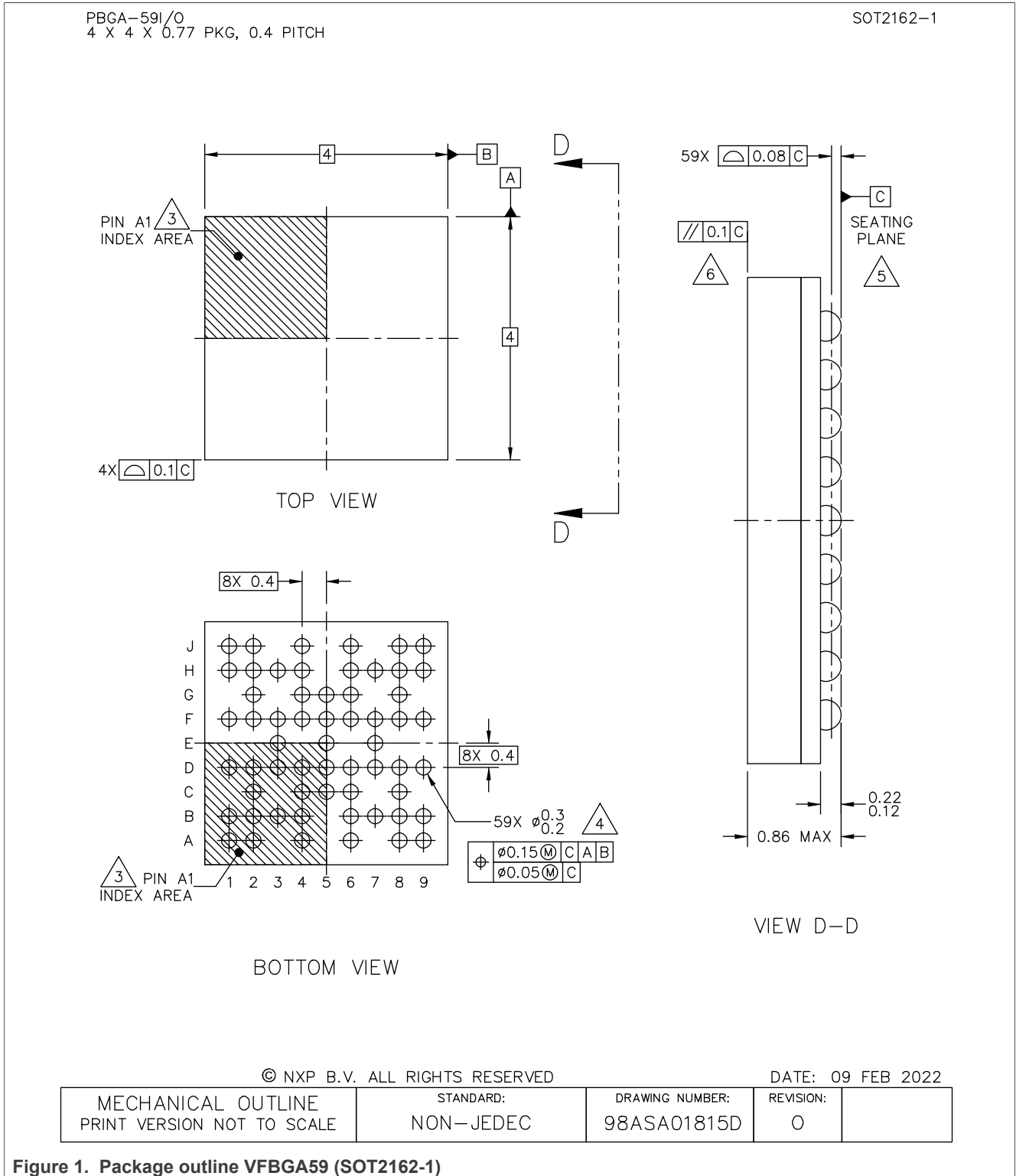
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	4	-	mm
package width	-	4	-	mm
seated height	-	0.77	-	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	59	-	



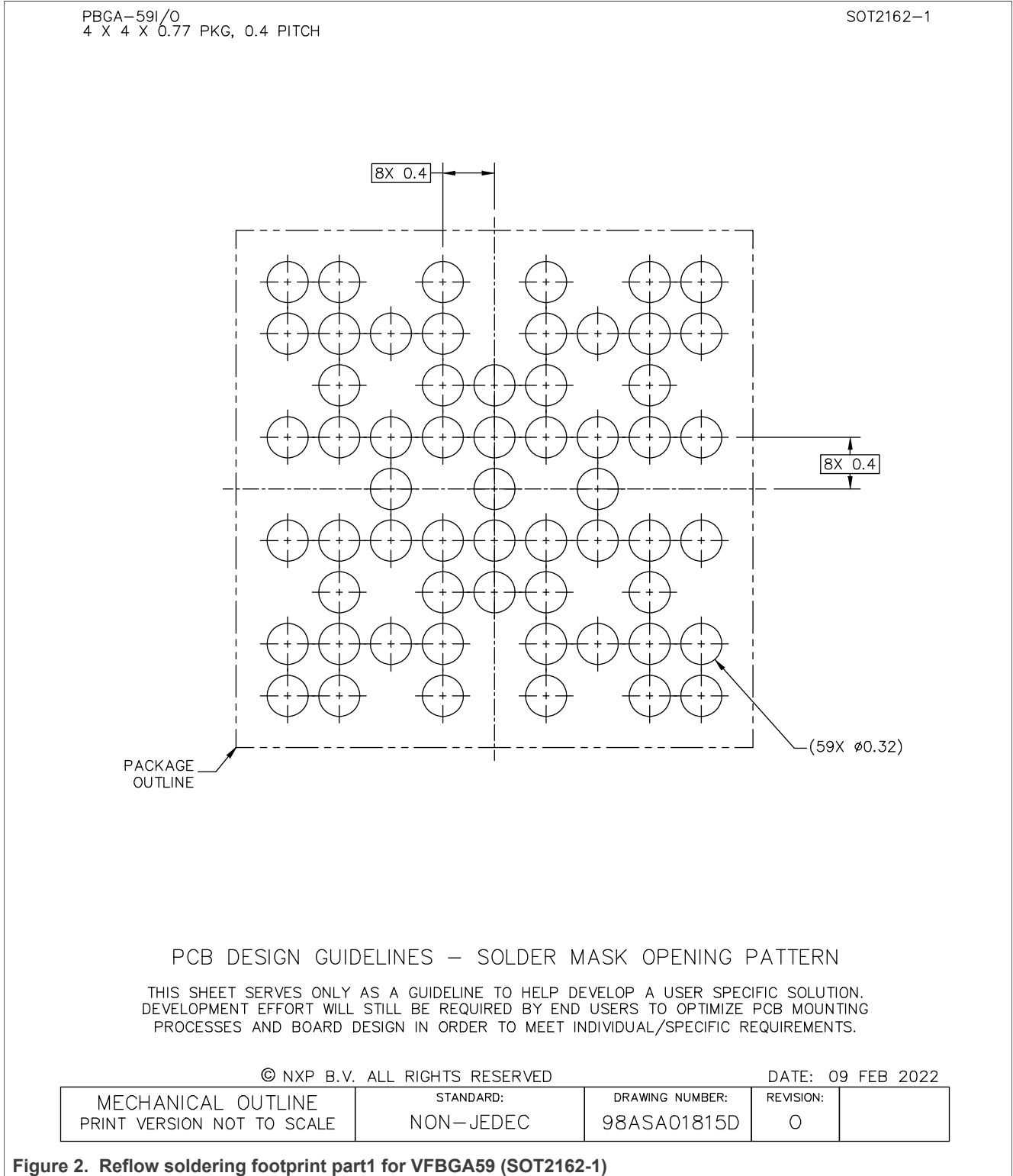
VFBGA59, very thin fine-pitch ball grid array package, 59 terminals, 0.4 mm pitch, 4 mm x 4 mm x 0.77 mm body

2 Package outline



VFBGA59, very thin fine-pitch ball grid array package, 59 terminals, 0.4 mm pitch, 4 mm x 4 mm x 0.77 mm body

3 Soldering



VFBGA59, very thin fine-pitch ball grid array package, 59 terminals, 0.4 mm pitch, 4 mm x 4 mm x 0.77 mm body

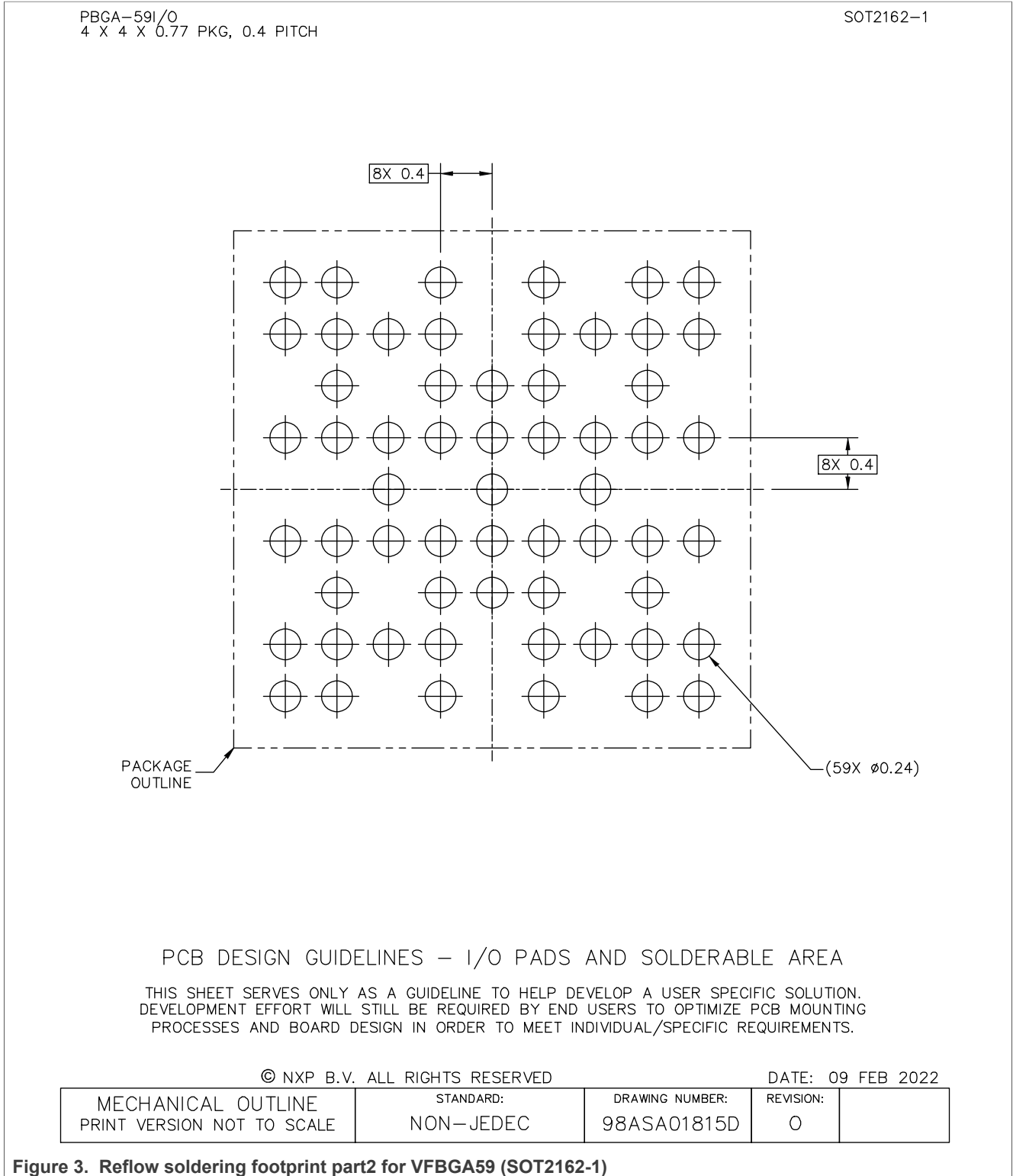


Figure 3. Reflow soldering footprint part2 for VFBGA59 (SOT2162-1)

VFBGA59, very thin fine-pitch ball grid array package, 59 terminals, 0.4 mm pitch, 4 mm x 4 mm x 0.77 mm body

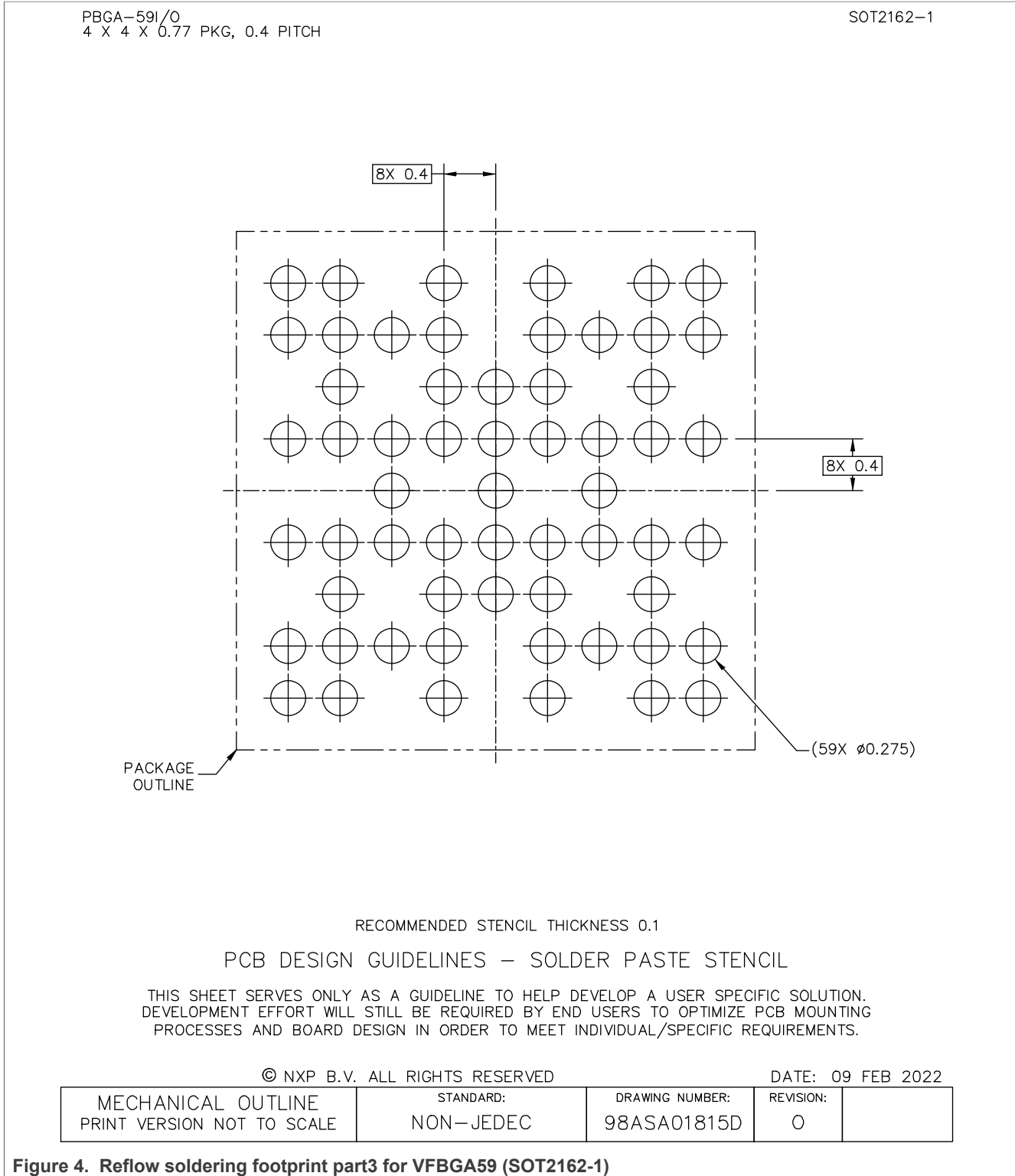


Figure 4. Reflow soldering footprint part3 for VFBGA59 (SOT2162-1)

VFBGA59, very thin fine-pitch ball grid array package, 59 terminals, 0.4 mm pitch, 4 mm x 4 mm x 0.77 mm body

PBGA-59I/O  
4 X 4 X 0.77 PKG, 0.4 PITCH

SOT2162-1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

© NXP B.V. ALL RIGHTS RESERVED

DATE: 09 FEB 2022

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01815D	REVISION: 0	
--	------------------------	--------------------------------	----------------	--

Figure 5. Package outline note VFBGA59 (SOT2162-1)

---

VFBGA59, very thin fine-pitch ball grid array package, 59 terminals, 0.4 mm pitch, 4 mm x 4 mm x 0.77 mm body

## 4 Legal information

---

### Disclaimers

**Limited warranty and liability** — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of NXP Semiconductors.

**Right to make changes** — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

---

VFBGA59, very thin fine-pitch ball grid array package, 59 terminals, 0.4 mm pitch, 4 mm x 4 mm x 0.77 mm body

## Contents

---

1	Package summary .....	1
2	Package outline .....	2
3	Soldering .....	3
4	Legal information .....	7